



SNAPHAT™ WITH INTEGRATED BATTERY AND CRYSTAL

FEATURES

- Detachable Unit Allowing Replacement
- Integrated 6-pF Watch Crystal for Real-Time Clock Operation
- Integrated Lithium Coin Cell for Nonvolatile Memory Backup
- Protects Battery and Crystal From Conditions Associated with Surface Mount Soldering
- For Use With bq4802YDSH and bq4802LYDSH
- Keyed Insertion to Avoid Incorrect Attachment

APPLICATIONS

- Telecommunications Base Stations
- Servers
- Handheld Data Collection Equipment

DESCRIPTION

The bq48SH-28x6 is the top section suitable for any SOIC (DSH) packaged IC including the bq4802YDSH or bq4802LYDSH parallel real-time clock (RTC) and NVSRAM controller.

The fully integrated SNAPHAT™ includes a 6-pF watch crystal and lithium coin cell with 48 mAh of capacity.

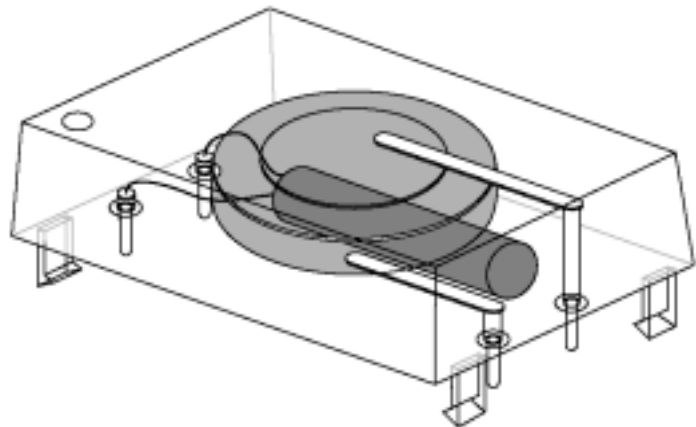
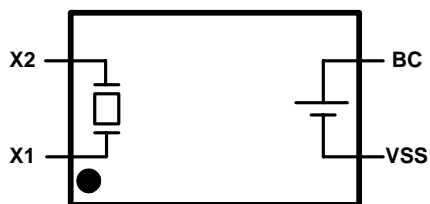
The SNAPHAT™ is designed to be attached after the DSH packaged base SOIC has been soldered preventing the battery and crystal being over-stressed by the soldering temperatures.

AVAILABLE OPTIONS

TA	PACKAGED DEVICES	SYMBOL
	SNAPHAT™† (NSH)	
0°C to 70°C	bq48SH-28x6NSH	bq48SH-28x6

† The SNAPHAT™ package is available taped and reeled. Add an R suffix to the device type (e.g. bq48SH-28x6NSHR to order quantities of 2,500 devices per reel.

CONNECTION DIAGRAMS



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SNAPHAT is a trademark of STMicroelectronics.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

bq48SH-28x6

SLUS508A – DECEMBER 2001 REVISED – JUNE 2002

absolute maximum ratings over operating free-air temperature (unless otherwise noted)†

Operating temperature range, T_J 0°C to 70°C
Storage temperature range, T_{stg} -40°C to 85°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds 260°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

	TYP	UNIT
Nominal battery voltage, V_{CC}	2.8	V
Nominal battery capacity	48	mAh

crystal specifications (DT-35 or equivalent)

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
f_O Oscillation frequency			32.768		kHz
C_L Load capacitance			6		pF
T_P Temperature turnover point		20	25	30	°C
k Parabolic curvature constant				-0.042	ppm/°C
Q Quality factor		40,000	70,000		
R_1 Series resistance				45	k Ω
C_O Shunt capacitance			1.1	1.8	pF
C_O/C_1 Capacitance ratio			430	600	
D_L Drive level				1	μW
$\Delta f/f_O$ Aging (first year at 25°C)			1		ppm

TERMINAL FUNCTIONS

TERMINAL		I/O	DESCRIPTION
NAME	NO.		
BC	3	O	Battery positive terminal
VSS	2	I	Battery negative terminal
X1	1	I	Crystal input
X2	4	O	Crystal output

functional description

connections

The SOIC (DSH) is connected to the SNAPHAT™ containing the battery and crystal through four pins that insert into four press-fitted sockets in the SOIC (DSH) where the contact area is gold plated. Each of the sockets internally contains six independent contacts to ensure solid reliable connectivity and minimize contact resistance.

Four molded retaining clips on the SNAPHAT™ also help fasten the SOIC (DSH), ensuring mechanical and electrical connection even under severe mechanical shock and vibration. The combined SOIC (DSH) and SNAPHAT assembly can sustain shock levels in excess of 100 g without separating. This package also passes variable frequency testing in accordance with MIL-STD-883, method 2007.2, condition A.

Figure 1 illustrates the effect of repeated insertion and extraction of the SNAPHAT™ top to the SOIC (DSH). The force required to extract the SNAPHAT™, and then to re-insert it, reduces each time. After three or four extractions, though, the reduction starts to become unnoticeable, and the force required remains at a fairly constant figure. Typically, though, the SNAPHAT needs to be extracted and re-inserted only once in its lifetime.

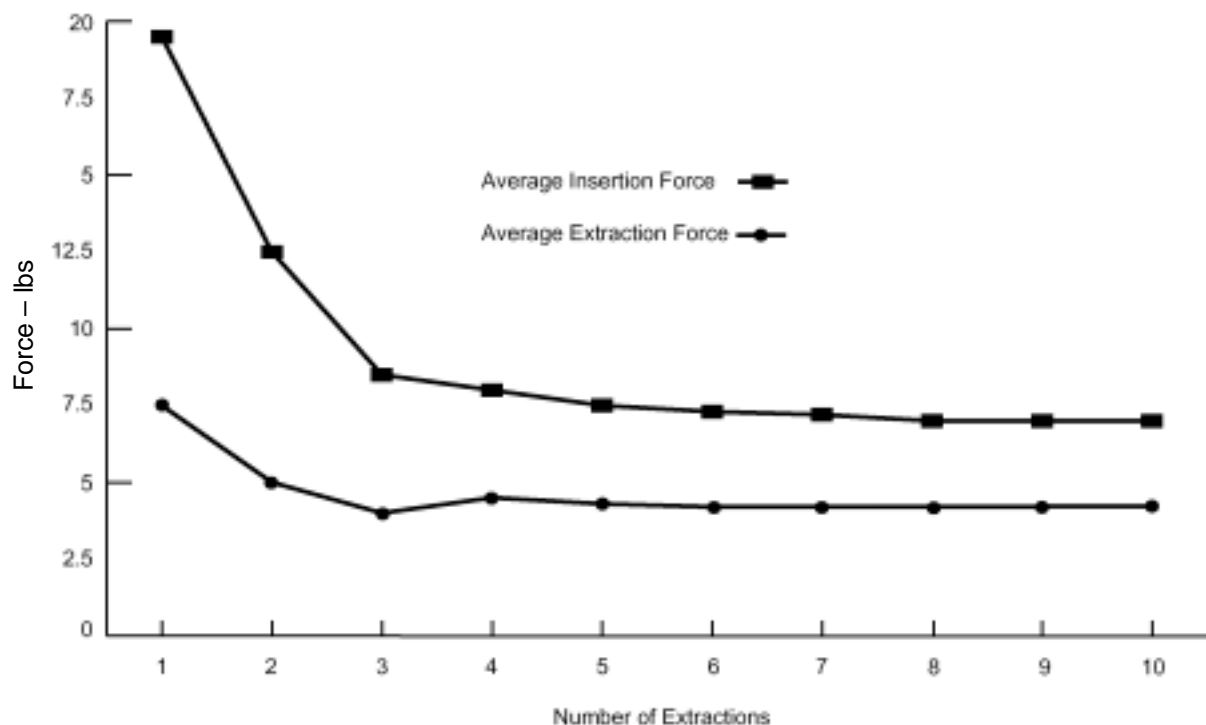


Figure 1. SNAPHAT Insertion and Extraction Forces

functional description (continued)

battery characteristics

Figure 2 illustrates the lithium coin cell discharge rate for a given load. This demonstrates the characteristically flat voltage level supplied by the battery until very near the end of its life. These discharge levels have been greatly accelerated in comparison to the normal, actual usage.

UL recognition

The bq48SH-28x6 has been recognized by Underwriters Laboratories under their Component Recognition Program and carries UL File No. E89556.

battery life

The life expectancy of the battery is greatly affected by temperature and usage profiles. Figure 2 highlights the effective discharge during loading periods, but temperature during loading periods can greatly affect the effective run time as shown in Figure 3.

general notes

To remove the SNAPHAT® top for replacement, a DIP/IC extractor tool should be used. The SNAPHAT top should be grasped by the narrow end to avoid bending the pins.

CAUTION:

To avoid draining the battery, do NOT place SNAPHAT pins into conductive foam.

TYPICAL CHARACTERISTICS

**BR1225 LITHIUM COIN CELL DISCHARGE RATE
vs
CELL VOLTAGE**

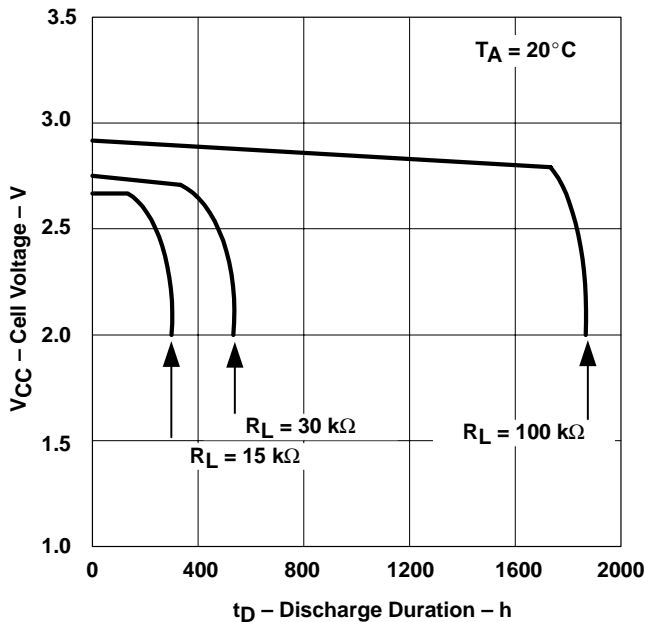
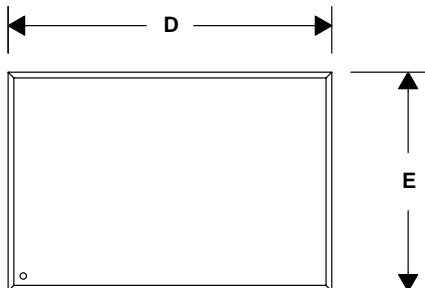


Figure 2

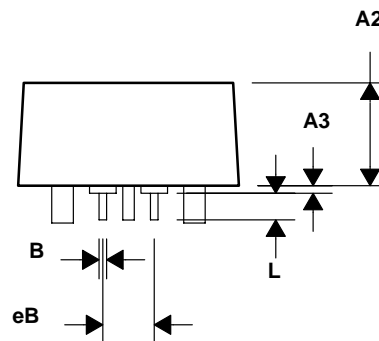
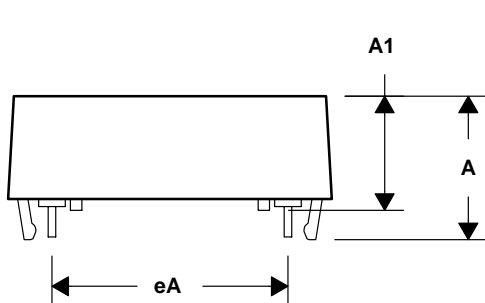
MECHANICAL DATA

NSH (R-PDIP-P4)

PLASTIC DUAL-IN-LINE



Dimension	Inches		Millimeters	
	Min.	Max.	Min.	Max.
A	–	0.385	–	9.78
A1	0.265	0.285	6.73	7.24
A2	0.255	0.275	6.48	6.99
A3	–	0.015	–	0.38
B	0.018	0.022	0.46	0.56
D	0.835	0.860	21.21	21.84
E	0.560	0.590	14.22	14.99
eA	0.612	0.628	15.54	15.95
eB	0.126	0.142	3.20	3.61
L	0.080	0.090	2.03	2.29



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NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
BQ48SH-28X6NSH	NRND	PDIP	NSH	4	23	TBD	Call TI	Call TI

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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